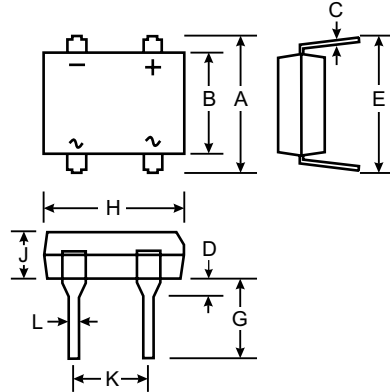


### Features

- Glass Passivated Die Construction
- Diffused Junction
- Low Forward Voltage Drop, High Current Capability
- Surge Overload Rating to 50A Peak
- Designed for Printed Circuit Board Applications
- Plastic Material - UL Flammability Classification 94V-0
- UL Listed Under Recognized Component Index, File Number E94661



DF-M		
Dim	Min	Max
A	7.40	7.90
B	6.20	6.50
C	0.22	0.30
D	1.27	2.03
E	7.60	8.90
G	3.81	4.69
H	8.13	8.51
J	2.40	3.40
K	5.00	5.20
L	0.46	0.58
All Dimensions in mm		

### Mechanical Data

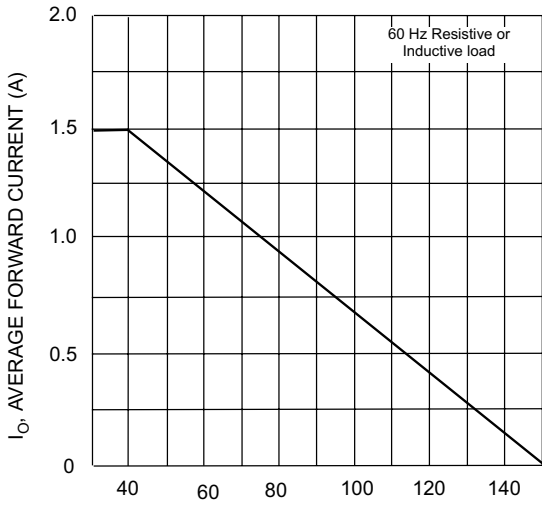
- Case: Molded Plastic
- Terminals: Solder Plated Leads, Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Approx. Weight: 0.38 grams
- Mounting Position: Any
- Marking: Type Number

### Maximum Ratings and Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

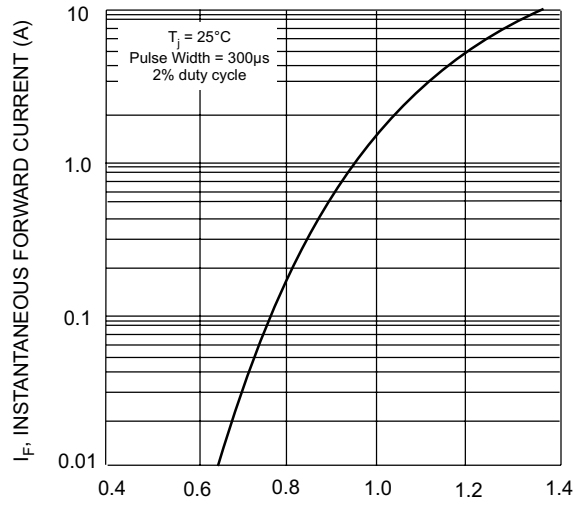
Single phase, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	DF 15005M	DF 1501M	DF 1502M	DF 1504M	DF 1506M	DF 1508M	DF 1510M	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V <sub>RWM</sub>								
DC Blocking Voltage	V <sub>R</sub>								
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T <sub>A</sub> = 40°C	I <sub>O</sub>	1.5							A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	50							A
Forward Voltage (per element) @ I <sub>F</sub> = 1.5A	V <sub>FM</sub>	1.1							V
Peak Reverse Current @ T <sub>A</sub> = 25°C at Rated DC Blocking Voltage @ T <sub>A</sub> = 125°C	I <sub>RM</sub>	10 500							μA
I <sup>2</sup> t Rating for Fusing (t<8.3ms)	I <sup>2</sup> t	10.4							A <sup>2</sup> s
Typical Junction Capacitance (Note 2)	C <sub>j</sub>	25							pF
Typical Thermal Resistance Junction to Ambient	R <sub>θJA</sub>	40							°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-65 to +150							°C

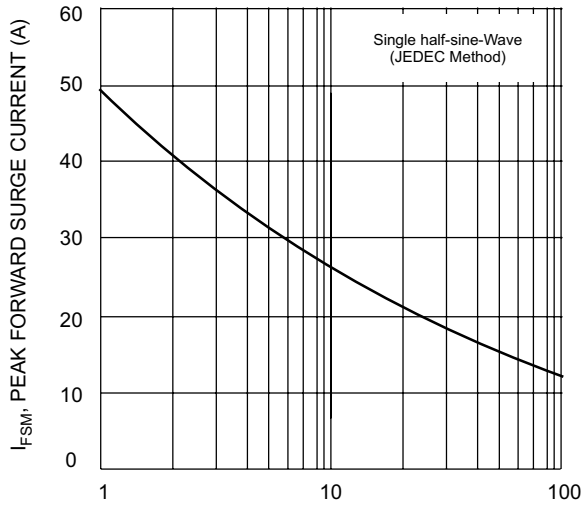
Notes: 1. Thermal resistance from junction to ambient mounted on PC board with 13 x 13mm (0.03mm thick) land areas.  
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.



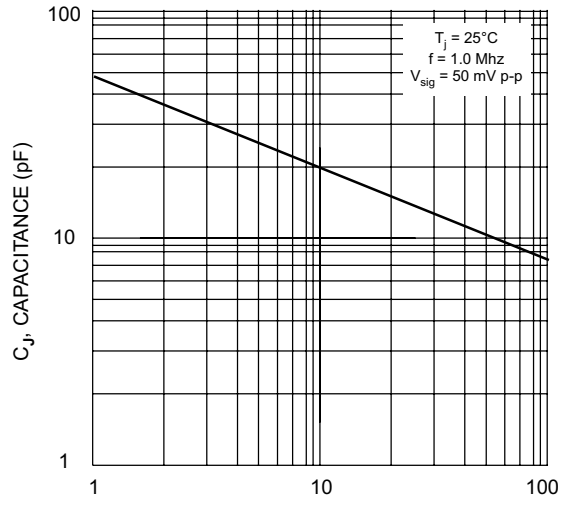
$T_A$ , AMBIENT TEMPERATURE (°C)  
Fig. 1 Output Current Derating Curve



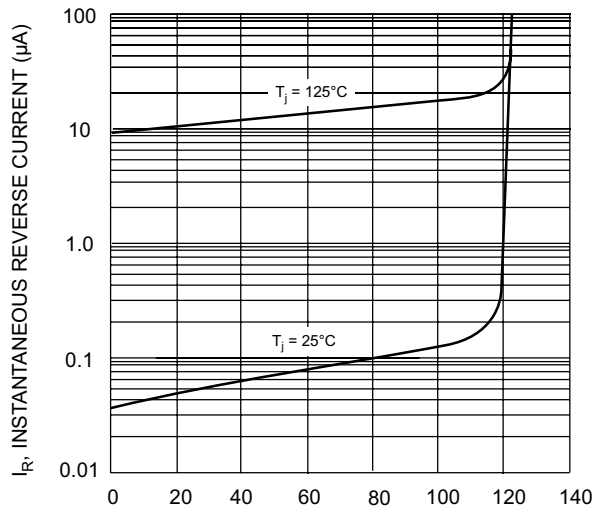
$V_F$ , INSTANTANEOUS FORWARD VOLTAGE (V)  
Fig. 2 Typ Forward Characteristics (per element)



NUMBER OF CYCLES AT 60 Hz  
Fig. 3 Max Non-Repetitive Peak Forward Surge Current



$V_R$ , REVERSE VOLTAGE (V)  
Fig. 4 Typ Junction Capacitance (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)  
Fig. 5 Typ Reverse Characteristics (per element)